

SEMICONDUCTOR COMPONENT AND METHOD OF MANUFACTURE

ABSTRACT

A semiconductor component and a method for manufacturing the semiconductor component, wherein the semiconductor component includes stacked semiconductor die. In accordance with embodiments, the semiconductor component includes a substrate having a component receiving area and a plurality of bond pads. A semiconductor chip is attached to the component receiving area. An electrical connector is coupled to the semiconductor chip and the substrate. A second semiconductor chip is mounted or attached to one of the ends of the electrical connector such that this end is positioned between the semiconductor chips. A second electrical connector is coupled between the second semiconductor chip and the substrate. A third semiconductor chip is mounted over or attached to the second electrical connector such that a portion is between the second and third semiconductor chips.

FIG. 7